

**REMARKS**

Claims 19, 21, 23 and 26 have been rejected under 35 USC 112(1) for not being enabled by the specification. The claims have been amended to overcome the rejection. Withdrawal of the rejection under 35 USC 112(1) is respectfully requested.

Claims 19, 21, 23 and 26 have been rejected under 35 USC 103(a) as being unpatentable over U.S. patent no. 5,635,847 ("Seidel") in view of U.S. patent no. 5,483,421 ("Gedney") and further in view of U.S. patent no. 5,680,936 ("Beers"). Applicants respectfully traverse these rejections because the cited references do not disclose or suggest every element of any claim, as the following analysis shows.

Independent claim 19 recites that solder balls are coupled to selected ones of the conductive pads and are not coupled to non-selected ones of the conductive pads (emphasis provided). Support for this limitation may be found in the specification at page 9 lines 4-9. Seidel, Gedney, and Beers, either singly or in combination, do not disclose or suggest coupling solder balls only to selected ones of the conductive pads while leaving the remaining conductive pads without solder balls. To the contrary, Seidel and Gedney both show that all conductive pads are to have solder balls attached. Beers does not even address the subject of solder balls.


Attorney Docket No. 042390.P5120D

**CONCLUSION**

For the foregoing reasons, Applicants submit that claims 19, 21, 23 and 26 are now in condition for allowance, and indication of allowance by the Examiner is respectfully requested. Applicants further submit that claims 22, 24 and 25 should now be considered and found allowable in view of the allowance of claims 19, 21, 23 and 26. If the Examiner has any questions concerning this application, he or she is requested to telephone the undersigned at the telephone number shown below as soon as possible. No fee is believed due in connection with this amendment. In this is incorrect, please charge any insufficiency or credit any overpayment to Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY SOLOKOFF TAYLOR &amp; ZAFMAN LLP

Date: 5-1-02

John Travis  
Reg. No. 43,203

12400 Wilshire Blvd  
Seventh Floor  
Los Angeles, California 90025-1026  
(512) 330-0844

## APPENDIX A

MARKED-UP COPY OF AMENDED CLAIMS

19. (Amended seven times) A method of assembling a multi-chip device comprising:
- providing an interposer having a first surface and a second surface;
  - populating the second surface with a plurality of conductive pads;
  - coupling [a] solder balls to [each of] selected ones of the plurality of conductive pads;
  - not coupling the solder balls to non-selected ones of the plurality of conductive pads;
- [soldering] coupling a plurality of cache memory devices and at least one passive device to the first surface to form a multi-chip subassembly, wherein the at least one passive device is selected from a group consisting of resistors, capacitors, and inductors;
- testing said plurality of cache memory devices on said interposer;
- [soldering] coupling said interposer to a substrate with the solder balls after said testing if said plurality of cache memory devices pass said testing; and
- [soldering] coupling a microprocessor device to the substrate.